502367857 05/31/2013

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
Harry-Hak-Lay Chuang	03/12/2013
Bao-Ru Young	03/12/2013
Wei Cheng Wu	03/12/2013
Yi-Ren Chen	03/12/2013
Ming Zhu	03/12/2013

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Rd. 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13792152

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 2012-0973/24061.2322

NAME OF SUBMITTER: Scott Matthews

PATENT REEL: 030525 FRAME: 0958 > \$40,00 13792152

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Signature:	/sm82918/
Date:	05/31/2013
Total Attachments: 3 source=13792152Assign#page1.tif source=13792152Assign#page2.tif source=13792152Assign#page3.tif	

PATENT REEL: 030525 FRAME: 0959

Docket No.: 2012-0973 / 234061.2322

Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

(1)	Harry Hak-Lay Chuang	of	51 Paya Lebar Crescent Singapore 536176
(2)	Bao-Ru Young	of	No. 7, Lane 1, Liujia 2nd Street, Zhubei City Hsinchu County 302, Taiwan R.O.C.
(3)	Wei Cheng Wu	of	10F., No. 196, Sec. 1, Shengli 7th Street Zhubei City, Hsinchu County 302 Taiwan R.O.C.
(4)	Yi-Ren Chen	of	No. 47, Xinle Street, Guishan Township Taoyuan County 333, Taiwan R.O.C.
(5)	Ming Zhu	of	Block 688F, #13-74, Woodlands Drive 75 Singapore 736688

have invented certain improvements in

STRUCTURE AND METHOD FOR STATIC RANDOM ACCESS MEMORY DEVICE OF VERTICAL TUNNELING FIELD EFFECT TRANSISTOR

for which we have executed an application for Letters Patent of the United States of America,

	of even date filed h		
X	filed on 3/10/2013	and assigned application number	_13/792,152; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any

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country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Harry Hak-Lay Chuang
Residence Address:	
	Inventor Signature
Inventor Name:	Bao-Ru Young
Residence Address:	No.7, Lane 1, Liujia 2nd Street, Zhubei City Hsinchu County 302, Taiwan R.O.C.
Dated: >613/3/	12 V BR/oury Inventor Signature
Inventor Name:	Wei Cheng Wu
Residence Address:	10F., No. 196, Sec. 1, Shengli 7th Street, Zhubei City Hsinchu County 302, Taiwan R.O.C.
Dated: 2013/3/	1/2 V Wei Gang Un Inventor Signature

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Customer No.: 000042717

Inventor Name:

Yi-Ren Chen

Residence Address:

No. 47, Xinle Street, Guishan Township, Taoyuan County 333

Taiwan R.O.C.

Dated: 2013/63/

Inventor Signature

Inventor Name:

Ming Zhu

Residence Address:

Block 688F, #13-74, Woodlands Drive 75

Singapore 736688

Dated:___

2013/03/12

Inventor Signature

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RECORDED: 05/31/2013

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